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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Norio KIMURA et al. :
Serial No. NEW : **Attn: Application Branch**
Filed May 25, 2001 : **Attorney Docket No. 2001-0660A**

SUBSTRATE POLISHING APPARATUS
AND SUBSTRATE POLISHING METHOD

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to examination of the above-referenced U.S. patent application please amend the application as follows:

IN THE CLAIMS

Please amend the claim as follows:

3. (Amended) A substrate polishing apparatus according to claim 1, further comprising dressing means for dressing said polishing surface of said polishing table or cleaning means for cleaning said polishing surface of said polishing table, and wherein said control mechanism controls said dressing means or said cleaning means between the polishing processes to effect the dressing or the cleaning of said polishing surface of said polishing table.

Please add the following new claim:

13. A substrate polishing apparatus according to claim 2, further comprising dressing means for dressing said polishing surface of said polishing table or cleaning means for cleaning

